

**ABSTRACT OF THE DISCLOSURE**

A method for manufacturing a high-efficiency thermal conductive base board for electrical connection with an electronic component includes the steps of: (a) placing a metal substrate in an electrolytic bath; (b) oxidizing the metal substrate in the electrolytic bath to form a metal oxide layer thereon through micro-arc oxidation; (c) forming a plurality of conductive contacts on the metal oxide layer for electrical connection with the electronic component.